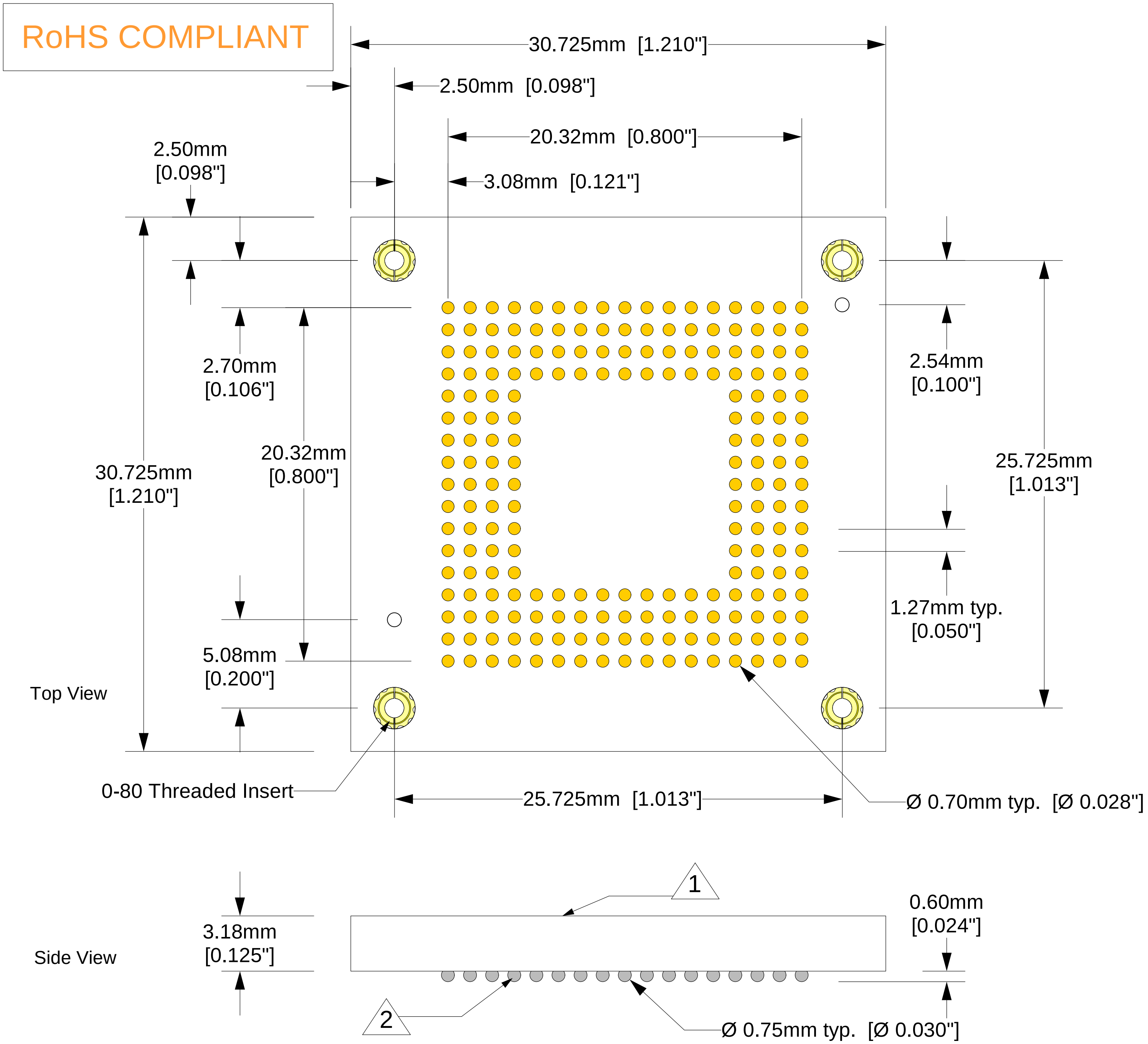
RoHS COMPLIANT



1 Substrate: 3.18mm ±0.25mm [0.125" ±0.001"] FR4/G10 or equivalent high temp material. 17µm [1/2 oz.] Cu clad. Au plating. (RoHS)

2 Solder ball: Sn96.5Ag3.0Cu0.5

Description: BGA Surface Mount Adaptor
208 position surface mount land pattern to solder balls. To be used with GHz sockets.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA208A-B-05F Drawing	Status: Released	Scale: 3:1	Rev: A
© 2006 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Suite 400 Burnsville MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: S.Natarajan File: SF-BGA208A-B-05F Dwg	Date: 5/13/06 Modified:	